

PJQ5514S6C-AU

30V N-Channel Enhancement Mode MOSFET

Voltage

30 V

Current

525 A

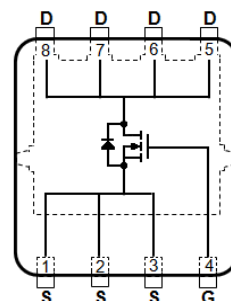
Features

- $R_{DS(ON)}$, $V_{GS}@10V$, $I_D@20A<0.64m\Omega$
- $R_{DS(ON)}$, $V_{GS}@4.5V$, $I_D@20A<0.97m\Omega$
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

- Case : DFN5060XC-8L Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.098 grams

DFN5060XC-8L



Maximum Ratings and Thermal Characteristics ($T_A=25^{\circ}C$ unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ^(Note 3)	$T_C=25^{\circ}C$	I_D	525	A
	$T_C=100^{\circ}C$		370	
Pulsed Drain Current ^(Note 1)	$T_C=25^{\circ}C$	I_{DM}	930	
Power Dissipation	$T_C=25^{\circ}C$	P_D	268	W
	$T_C=100^{\circ}C$		134	
Continuous Drain Current ^(Note 4)	$T_A=25^{\circ}C$	I_D	62	A
	$T_A=70^{\circ}C$		52	
Power Dissipation	$T_A=25^{\circ}C$	P_D	3.8	W
	$T_A=70^{\circ}C$		2.6	
Single Pulse Avalanche Current ^(Note 5)		I_{AS}	32	A
Single Pulse Avalanche Energy ^(Note 5)		E_{AS}	378	mJ
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55~175	$^{\circ}C$
Thermal Resistance ^(Note 4)	Junction to Case	$R_{\theta JC}$	0.56	$^{\circ}C/W$
	Junction to Ambient	$R_{\theta JA}$	40	

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Electrical Characteristics (T_A=25°C unless otherwise noted)

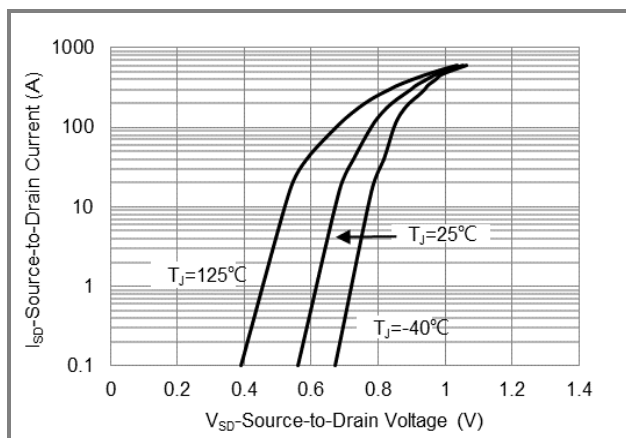
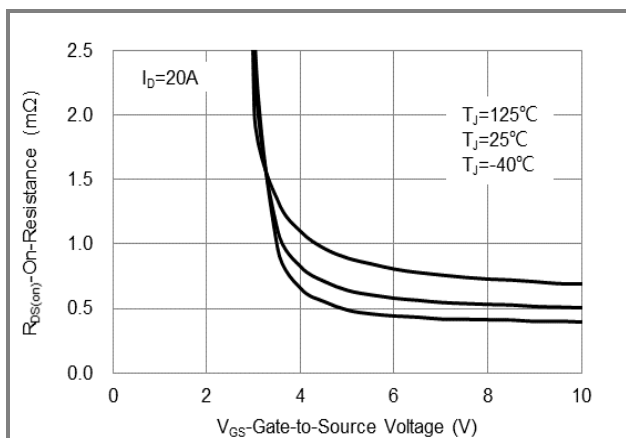
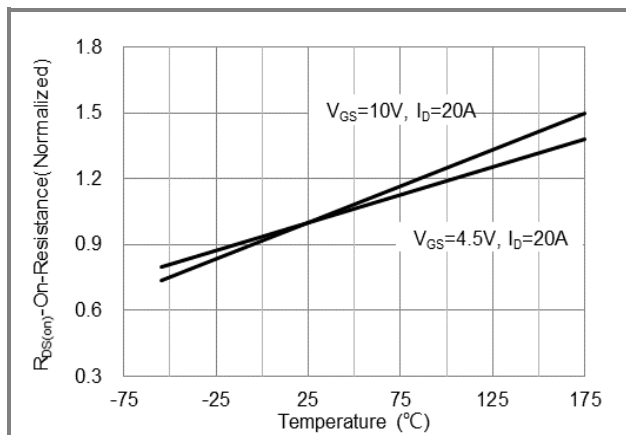
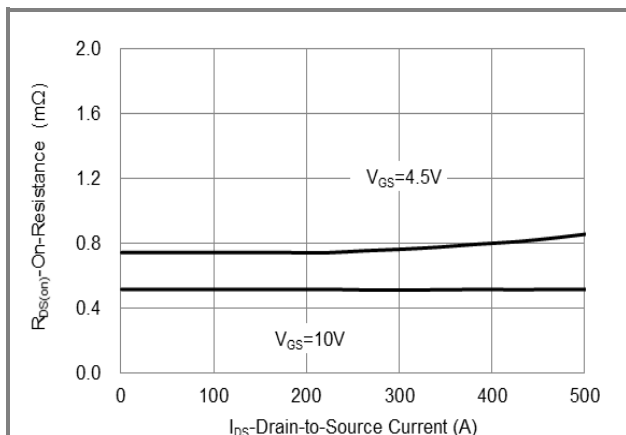
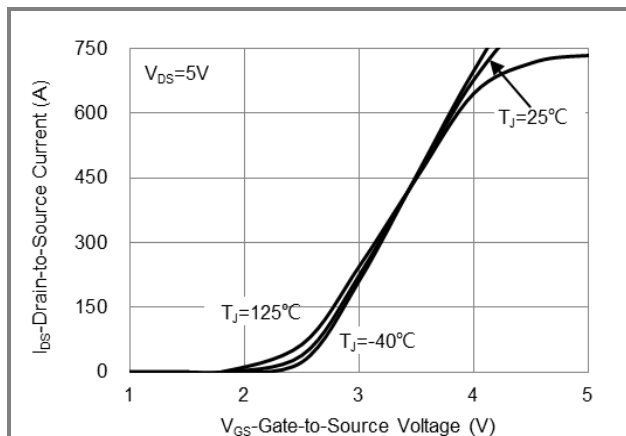
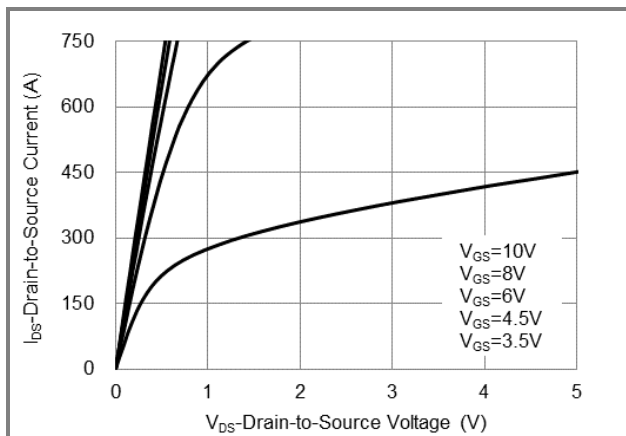
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.1	1.6	2.3	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	0.51	0.64	mΩ
		V _{GS} =4.5V, I _D =20A	-	0.74	0.97	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Dynamic ^(Note 6)						
Total Gate Charge	Q _g	V _{DS} =24V, I _D =20A, V _{GS} =10V	-	122	160	nC
Gate-Source Charge	Q _{gs}		-	14.5	-	
Gate-Drain Charge	Q _{gd}		-	24	-	
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1MHz	-	7402	9700	pF
Output Capacitance	C _{oss}		-	2724	3600	
Reverse Transfer Capacitance	C _{rss}		-	140	210	
Gate resistance	R _g	f=1MHz	-	3.3	-	Ω
Turn-On Delay Time	td _(on)	V _{DS} =24V, I _D =20A, V _{GS} =10V, R _G =3Ω (Note 2)	-	12	-	ns
Turn-On Rise Time	tr		-	27	-	
Turn-Off Delay Time	td _(off)		-	129	-	
Turn-Off Fall Time	tf		-	84	-	
Drain-Source Diode						
Diode Forward Current	I _S	T _C =25°C (Package Limit)	-	-	302	A
Pulsed Diode Forward Current	I _{SM}		-	-	930	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	-	0.73	1.3	V
Reverse Recovery Time	T _{rr}	V _{DD} =24V, V _{GS} =0V,	-	72	-	ns
Reverse Recovery Charge	Q _{rr}	I _S =20A, dI _S /dt=100A/us	-	82	-	nC

NOTES :

1. Pulse width≤100us, Duty cycle≤2%.
2. Essentially independent of operating temperature typical characteristics.
3. Chip capability with an R_{θJC}=0.56°C/W, Pakage limited 120A.
4. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
5. E_{AS} is calculated based on the condition of L=1mH, I_{AS}=27.5A, V_{DD}=30V, V_{GS}=10V. 100% test at L=0.5mH, I_{AS}=32A in production.
6. Guaranteed by design, not subject to production testing.

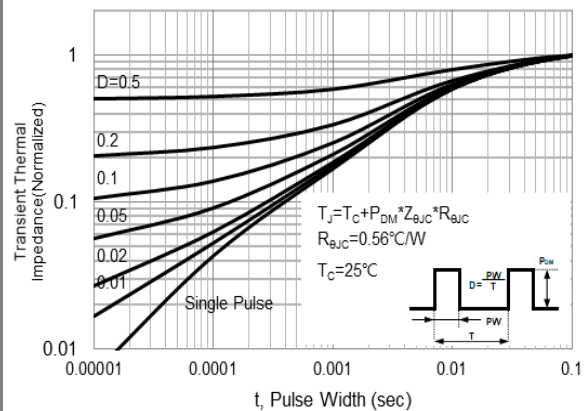
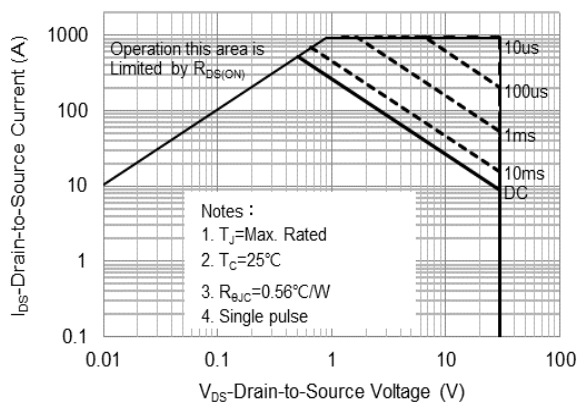
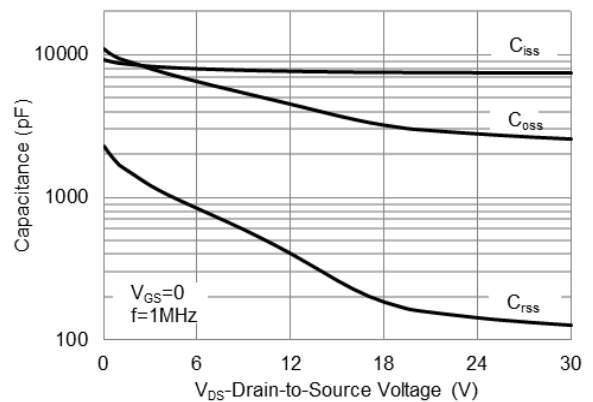
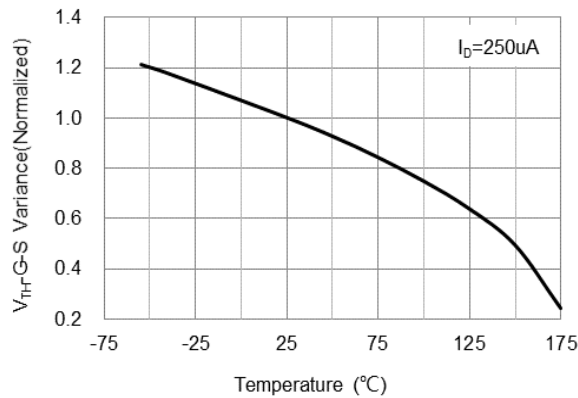
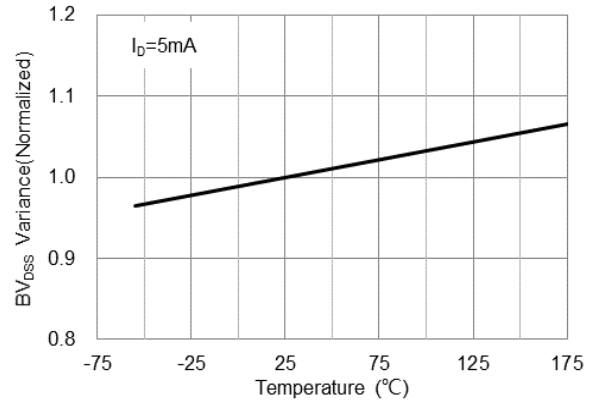
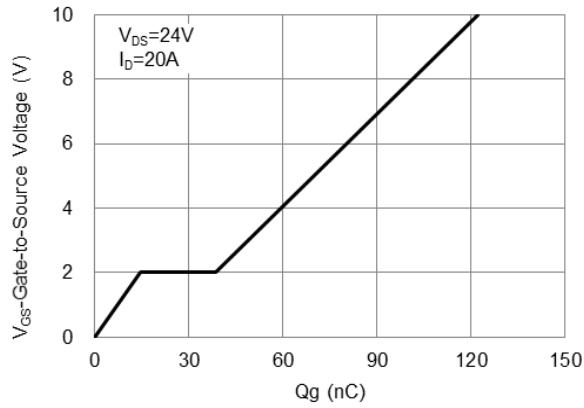
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TYPICAL CHARACTERISTIC CURVES



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TYPICAL CHARACTERISTIC CURVES

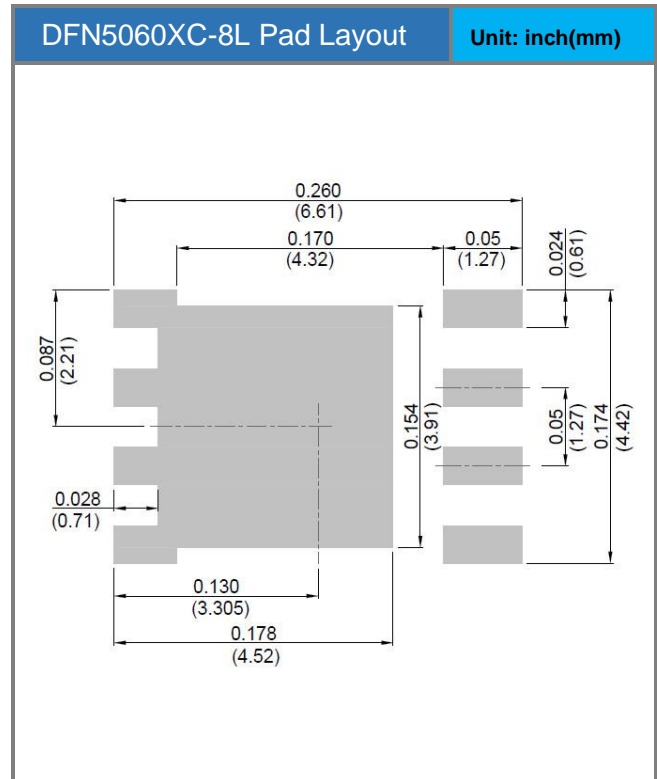
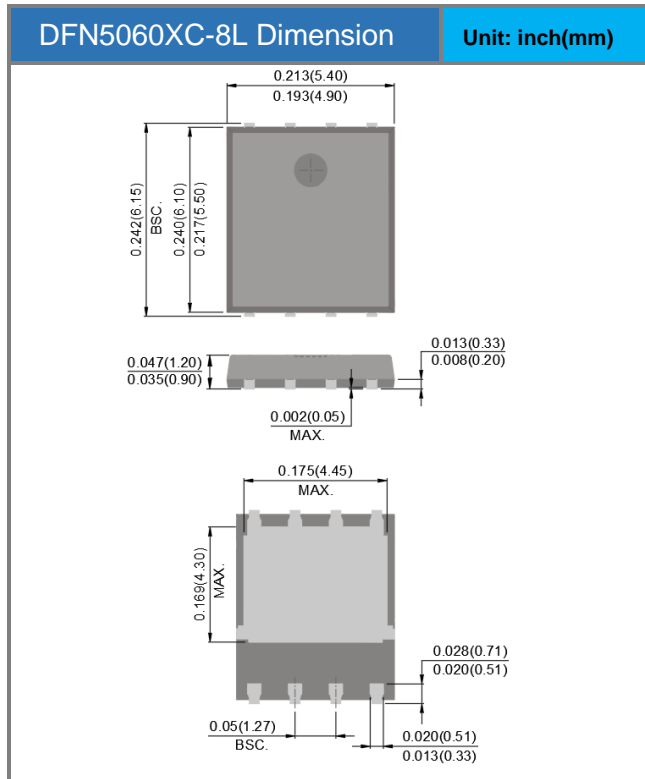


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Product and Packing Information

Part No.	Package Type	Packing Type	Marking
PJQ5514S6C-AU	DFN5060XC-8L	3K pcs / 13" reel	5514S6C

Packaging Information & Mounting Pad Layout



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